

## General Description

The MY60N06NE3 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

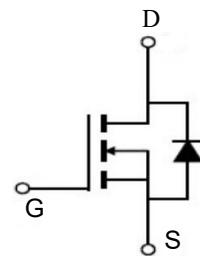
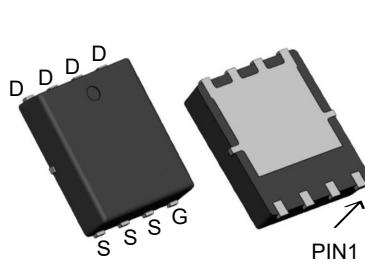


## Features

$V_{DSS}$	60	V
$I_D$	60	A
$R_{DS(ON)}(\text{at } V_{GS}=10\text{V})$	6.9	$\text{m}\Omega$
$R_{DS(ON)}(\text{at } V_{GS}=4.5\text{V})$	10	$\text{m}\Omega$

## Application

- Battery protection
- Load switch
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY60N06NE3	PDFN3*3-8	MY60N06NE3	5000

## Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Größe	Wert	Einheit	Wert
$X_{OU}$	$0.1 \mu\text{A}$	$\text{A}$	$1 \mu\text{A}$
$X_{OU}$	$0.1 \mu\text{A}$	$\text{A}$	$\pm 20$
$I_D @ T_c = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}^1$	A	60
$I_D @ T_c = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}^1$	A	35
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	A	130
EAS	Single Pulse Avalanche Energy <sup>3</sup>	mJ	48
$I_{AS}$	Avalanche Current	A	35
$P_D @ T_c = 25^\circ\text{C}$	Total Power Dissipation <sup>4</sup>	W	39
$T_{STG}$	Storage Temperature Range	$^\circ\text{C}$	-55 to 150
$T_J$	Operating Junction Temperature Range	$^\circ\text{C}$	-55 to 150
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	$^\circ\text{C/W}$	60
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	$^\circ\text{C/W}$	3.2

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=12\text{A}$	---	6.9	8.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	---	10.0	15	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.4	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=32\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	1.7	---	$\Omega$
$Q_g$	Total Gate Charge (4.5V)	$V_{\text{DS}}=20\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_D=12\text{A}$	---	5.8	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	3	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	1.2	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\Omega$	---	14.3	---	$\text{ns}$
$T_r$	Rise Time		---	5.6	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	20	---	
$T_f$	Fall Time		---	11	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	690	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	193	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	38	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	60	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=31\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation

### Typical Characteristics

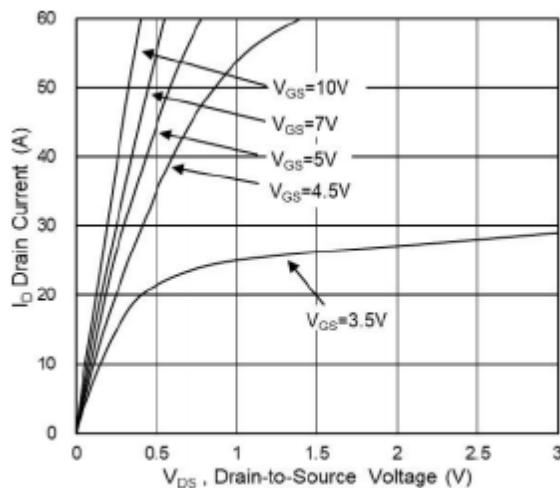


Fig.1 Typical Output Characteristics

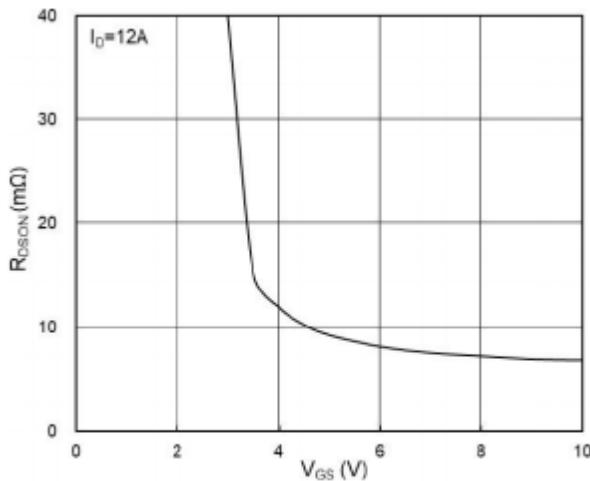


Fig.2 On-Resistance vs G-S Voltage

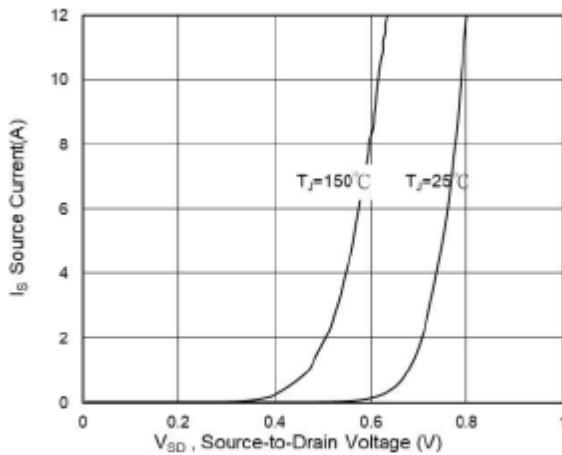


Fig.3 Source Drain Forward Characteristics

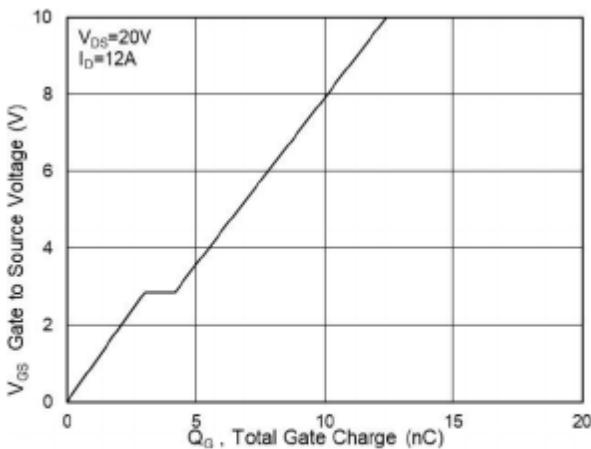
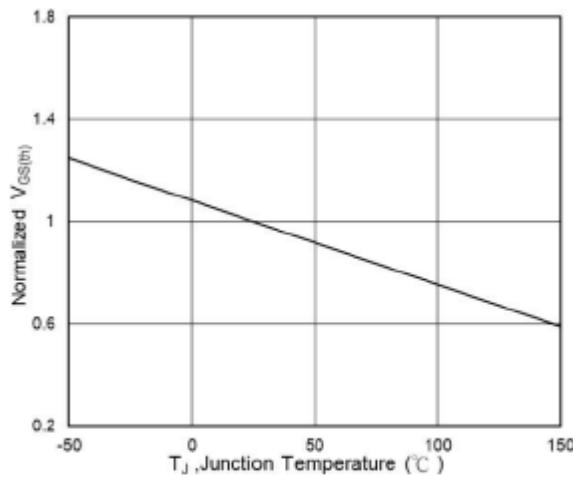
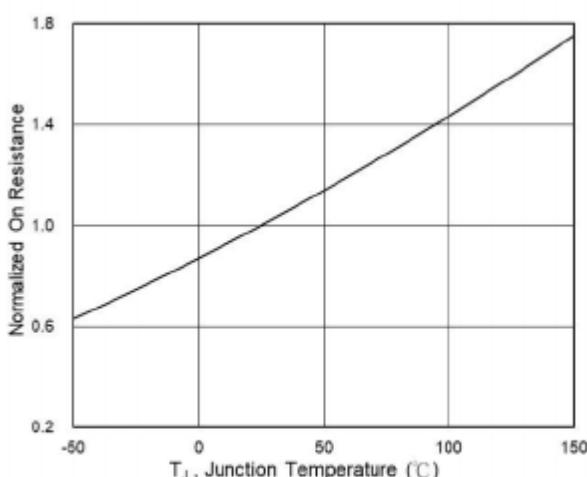


Fig.4 Gate-Charge Characteristics

Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$ Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$

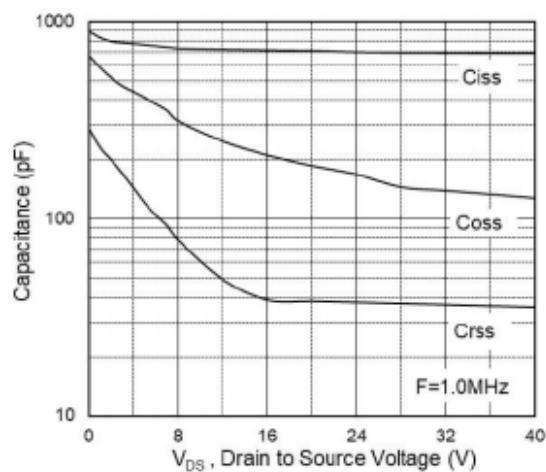


Fig.7 Capacitance

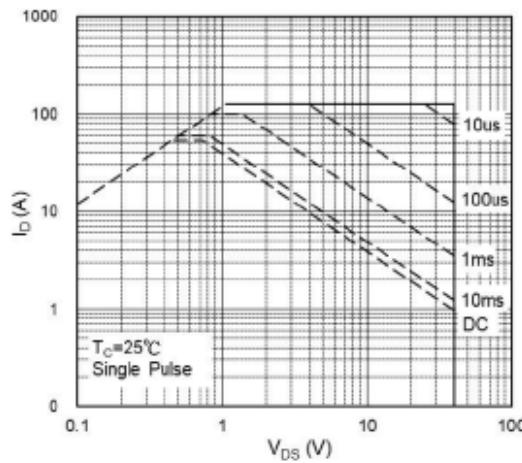


Fig.8 Safe Operating Area

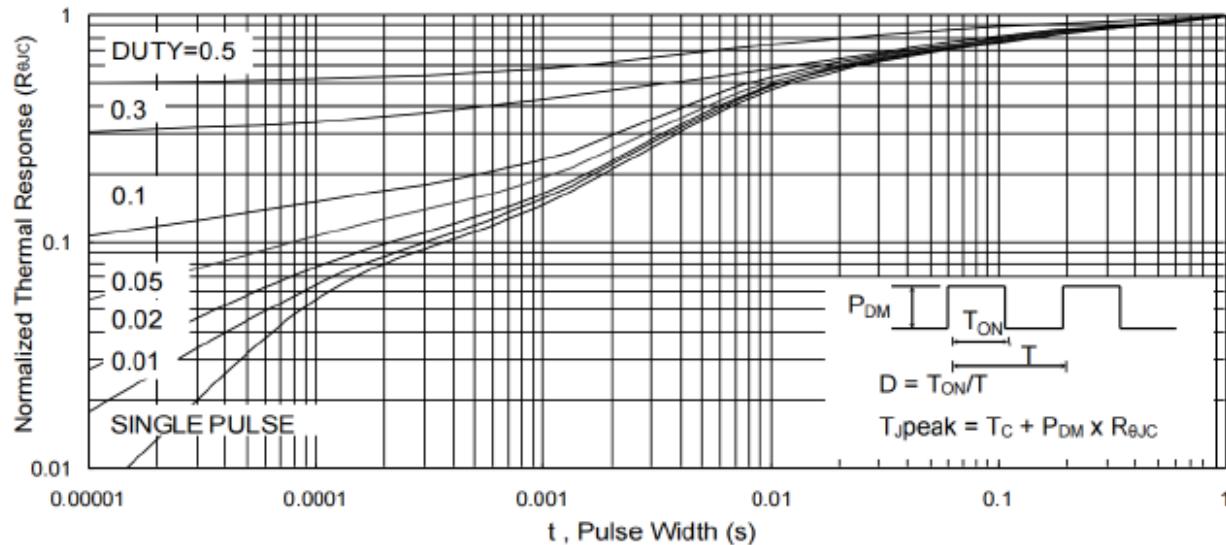


Fig.9 Normalized Maximum Transient Thermal Impedance

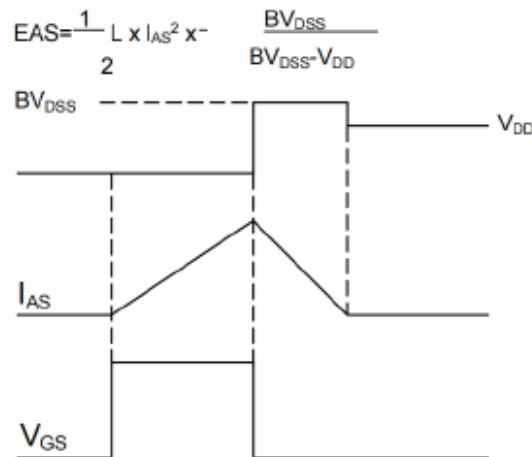
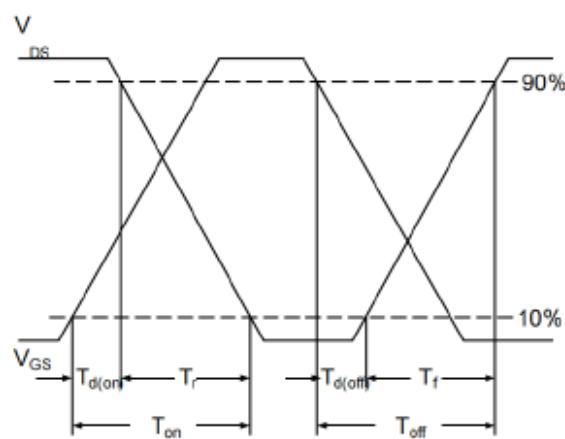
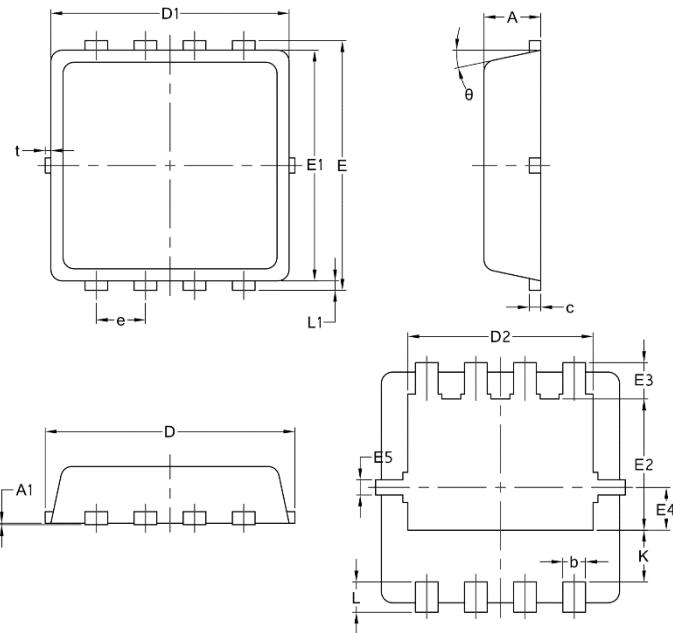


Fig.11 Unclamped Inductive Waveform

**Package Mechanical Data-DFN3\*3-8L-JQ Single**


Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
$\Phi$	10	12	14